

## pSEMI MATERIAL DECLARATION FORM

<b>Product:</b>	<b>PE42424</b>
<b>Ordering Codes:</b>	<b>PE42424A-Z</b>
<b>Description:</b>	<b>UltraCMOS® SPDT RF Switch, 100 MHz–8.5 GHz</b>
<b>Package:</b>	<b>6L 1.5 X 1.5 DFN</b>
<b>Environmental Compliance</b>	<b>EU RoHS2 Directive 2011/65/EC, REACH - EU ECHA SVHC, Arsenic Free, JIG 101 - EIA/EICTA/JEITA, Halogen Free - IEC61249-2-21, PFOS Free - 2006/122/EC, Antimony Trioxide Free</b>
<b>Lead Finish</b>	<b>NiPdAu</b>
<b>Availability</b>	<b>Now</b>

Component	Material	CAS Number	Weight (mg)	%	PPM
Die	Sapphire (Al <sub>2</sub> O <sub>3</sub> )	1344-28-1	0.424912	10.40%	103,988.25
LeadFrame	Copper (Cu)	7440-50-8	1.800000	44.05%	440,512.27
LeadFrame	Silicon (Si)	7440-21-3	0.014000	0.34%	3,426.21
LeadFrame	Magnesium (Mg)	7439-95-4	0.003300	0.08%	807.61
LeadFrame	Nickel (Ni)	7440-02-0	0.086000	2.10%	21,046.70
LeadFrame	Gold (Au)	7440-57-5	0.000570	0.01%	139.50
LeadFrame	Silver (Ag)	7440-22-4	0.000420	0.01%	102.79
LeadFrame	Palladium (Pd)	7440-05-3	0.000950	0.02%	232.49
Die Attach	Silver (Ag)	7440-22-4	0.159000	3.89%	38,911.92
Die Attach	High Boiling Methacrylate	Trade secret	0.013000	0.32%	3,181.48
Die Attach	Bismaleimide Resin	Trade secret	0.011000	0.27%	2,692.02
Gold Wire	Gold (Au)	7440-57-5	0.057000	1.39%	13,949.56
Mold Compound	Epoxy Resin - 1	Trade secret	0.056000	1.37%	13,704.83
Mold Compound	Epoxy Resin - 2	Trade secret	0.032000	0.78%	7,831.33
Mold Compound	Phenol Resin	Trade secret	0.056000	1.37%	13,704.83
Mold Compound	Amorphous Silica	60676-86-0	1.201000	29.39%	293,919.58
Mold Compound	Crystal Silica	14808-60-7	0.080000	1.96%	19,578.32
Mold Compound	Carbon Black	1333-86-4	0.003000	0.07%	734.19
Mold Compound	Magnesium Hydroxide and Zinc Hy	Trade secret	0.088000	2.15%	21,536.16
<b>Total Weight (mg)</b>			<b>4.086152</b>	100.00%	1,000,000

